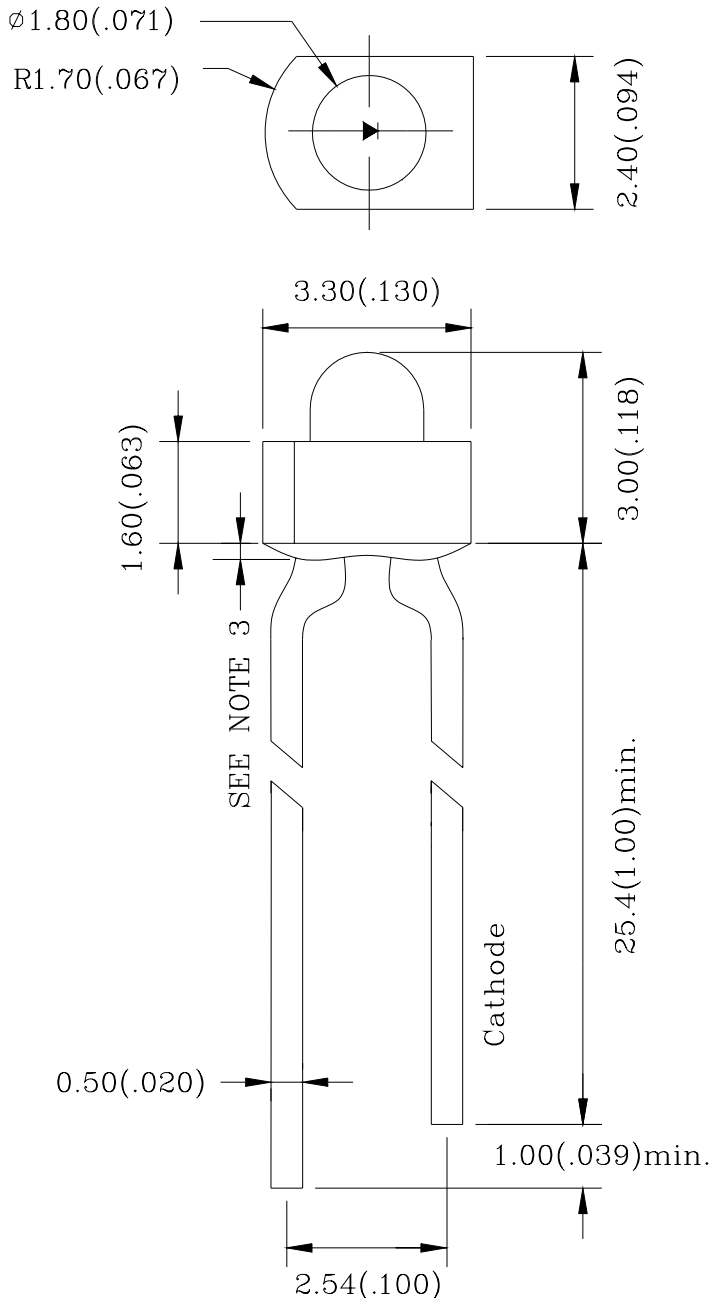


PACKAGE DIMENSIONS



- Note:
1. All Dimensions are in millimeters.
  2. Tolerance is  $\pm 0.25\text{mm}$  (0.010 ") Unless otherwise specified.
  3. Protruded resin under flange is 1.5mm (0.059 ") max.
  4. Lead spacing is measured where the leads emerge from the package.
  5. Specification are subject to change without notice



# 1.80 mm DIA TOWER TYPE LED LAMP

## HH-1.8RC-35

REV:A / 1

### FEATURES

- \* 1.8 mm DIA TOWER TYPE LED LAMP
- \* HIGH LUMINOUS INTENSITY OUTPUT.
- \* LOW POWER CONSUMPTION.
- \* HIGH EFFICIENCY.
- \* VERSATILE MOUNTING ON P.C. BOARD OR PANEL.
- \* I.C. COMPATIBLE.

### CHIP MATERIALS

- \* Dice Material : GaAlInP
- \* Light Color : RED
- \* Lens Color : WATER CLEAR

### ABSOLUTE MAXIMUM RATING : ( Ta = 25°C )

SYMBOL	PARAMETER	ULTRA RED	UNIT
PAD	Power Dissipation Per Chip	80	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	30	mA
IPF	Peak Forward Current Per Chip (Duty – 0.1, 1KHz)	60	mA
—	Derating Linear From 25°C Per Chip	0.40	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	

Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds

### ELECTRO-OPTICAL CHARACTERISTICS : ( Ta = 25°C )

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.2		V
IR	Reverse Current	VR = 5V			100	μA
λD	Dominant Wavelength	IF = 20mA		628		nm
Δλ	Spectral Line Half-Width	IF = 20mA		20		nm
2θ1/2	Half Intensity Angle	IF = 20mA		35		deg
IV	Luminous Intensity	IF = 20mA		2250		mcd

